IN THE CLAIMS

1 (Currently Amended). A method comprising:

coupling a first and second surface of an electronic device in spaced apart relationship so as to form a region between said first and second surfaces;

forming a centrally located hole in one of said surfaces;

forming a plurality of radially displaced holes arranged at a substantially uniform radius from said centrally located hole; and

injecting an encapsulant between said first and second surfaces through said centrally located hole until the encapsulant reaches said radially displaced holes and thereafter stopping the injection of encapsulant through said centrally located hole and injecting encapsulant through said radially displaced holes ~~one of said holes~~.

Claims 2-3 (Canceled).

4 (Previously Amended). The method of claim 1 including injecting encapsulant through said centrally located hole until the encapsulant reaches said radially displaced holes and thereafter stopping the injection of encapsulant through said centrally located hole and injecting encapsulant through said radially displaced holes.

Claims 5-8 (Canceled).

9 (Original). The method of claim 1 including forming an electronic display.

Claims 10-18 (Canceled).

19 (Original). A method comprising:

injecting encapsulant into an electronic device at a first location; and

when the encapsulant reaches a second location spaced from said first location, injecting encapsulant at a location proximate to said second location.

20 (Original). The method of claim 19 including coupling a first and second surface of an electronic device and injecting encapsulant between said first and second surfaces.

21 (Original). The method of claim 20 including forming a centrally located hole and forming a plurality of radially displaced holes arranged at a substantially uniform radius from said centrally located hole.

22 (Original). The method of claim 21 including injecting encapsulant through said centrally located hole until the encapsulant reaches said radially displaced holes and thereafter stopping the injection of encapsulant through said centrally located hole and injecting encapsulant through said radially displaced holes.

23 (Original). The method of claim 19 including forming an electronic display.

24 (Original). The method of claim 19 including injecting encapsulant into a region between a pair of spaced plates.

25 (Original). The method of claim 24 including injecting encapsulant through one of said plates.

26 (Previously Added). A method comprising:

forming a centrally located hole in a first surface of an electronic device;

forming a plurality of radially displaced holes arranged at substantially uniform radius from said centrally located hole in a first or a second surface;

coupling the first and second surface of an electronic device; and

injecting an encapsulant between said first and second surfaces through said centrally located hole until the encapsulant reaches said radially displaced hole and thereafter stopping the injection from encapsulant through said centrally located hole and injecting encapsulant through said radially displaced holes.

27 (Previously Added). The method of claim 26 wherein injecting encapsulant causes encapsulant front to extend outwardly from the center of a region to be encapsulated between said first and second surfaces.

28 (Previously Added). The method of claim 26 including forming an electronic display.

29 (Previously Added). The method of claim 28 including injecting an encapsulant into a region between a pair of spaced parallel plates.